

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. (Currently Amended) A pattern forming method of forming film patterns by arranging droplets of a liquid material on a substrate, the method comprising the steps of:

defining a plurality of pattern forming areas on the substrate in which the film patterns are intended to be formed; and

sequentially arranging a plurality of droplets in the plurality of defined pattern forming areas to form the film patterns;

wherein the droplets are sequentially arranged by setting an arrangement order of the droplets to be substantially equal in the plurality of pattern forming areas; and

wherein a periphery portion of the film patterns is formed before an interior portion of the film patterns is formed; and

wherein the film patterns are line-shaped patterns, side portions in a line-width direction of the film patterns are first formed, and then central portions of the film patterns are formed.

2. (Original) The pattern forming method according to Claim 1,

wherein a plurality of unit areas having a lattice shape in which the droplets are arranged are defined on the substrate, and the droplets are arranged in a predetermined unit area of the plurality of unit areas.

3. (Original) The pattern forming method according to Claim 1,
wherein the droplets are arranged essentially simultaneously in the plurality of
pattern forming areas.

4. (Cancelled)

5. (Original) The pattern forming method according to Claim 1,
wherein the plurality of pattern forming areas are arranged and defined in a
predetermined direction, a plurality of discharge portions for arranging the droplets
are provided to correspond to the plurality of pattern forming areas, respectively, and
the droplets are arranged while moving the discharge portions in the arrangement
direction of the pattern forming areas.

6. (Original) The pattern forming method according to Claim 1,
wherein the liquid material comprises conductive particles.

7. (Currently Amended) A pattern forming method of forming line-shaped
film patterns by arranging droplets of a liquid material on a substrate, the method
comprising the steps of:

defining a plurality of pattern forming areas on the substrate in which the film
patterns are intended to be formed; and

arranging the plurality of droplets in the plurality of defined pattern forming
areas, the droplets overlapping a part of the pattern forming areas, to form the film
patterns,

wherein the arrangement of the droplets is set to be substantially equal in the plurality of pattern forming areas; and

wherein a periphery portion of the film patterns is formed before an interior portion of the film patterns is formed; and

wherein the film patterns are line-shaped patterns, side portions in a line-width direction of the film patterns are first formed, and then central portions of the film patterns are formed.

8. – 9. (Cancelled)

10. (Currently Amended) A method of manufacturing a device having wiring patterns, the method comprising:

a material arranging step of forming the wiring patterns by arranging droplets of a liquid material in a plurality of pattern forming areas which are defined on a substrate and in which the wiring patterns are intended to be formed,

wherein the material arranging step includes a step of forming the wiring patterns by sequentially arranging the plurality of droplets in the plurality of defined pattern forming areas; [[,]] and

wherein the droplets are sequentially arranged by setting an arrangement order of the droplets to be substantially equal in the plurality of pattern forming areas; and

wherein a periphery portion of the film patterns is formed before an interior portion of the film patterns is formed; and

wherein the film patterns are line-shaped patterns, side portions in a line-width direction of the film patterns are first formed, and then central portions of the film patterns are formed.

11. (Currently Amended) A method of manufacturing a device having wiring patterns, the method comprising:

a material arranging step of forming the wiring patterns by arranging droplets of a liquid material in a plurality of pattern forming areas which are defined on a substrate and in which the wiring patterns should be formed,

wherein the material arranging step includes a step of forming the wiring patterns by arranging the plurality of droplets in the plurality of defined pattern forming areas, the droplets overlapping a part of the pattern forming areas;

wherein the arrangement of the droplets is set to be substantially equal in the plurality of pattern forming areas; ~~and~~

wherein a periphery portion of the film patterns is formed before an interior portion of the film patterns is formed; and

wherein the film patterns are line-shaped patterns, side portions in a line-width direction of the film patterns are first formed, and then central portions of the film patterns are formed.

12. – 20. (Cancelled)